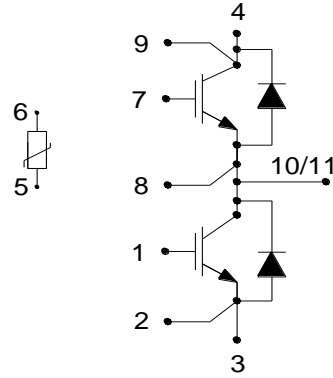


| 关键参数 | | Key Parameters | |
|---------------|------|----------------|---|
| V_{CES} | | 1700 | V |
| $V_{CE(sat)}$ | Typ. | 1.80 | V |
| I_C | Max. | 600 | A |
| $I_{C(RM)}$ | Max. | 1200 | A |

| 典型应用 | Typical Applications |
|-----------|---------------------------|
| ● 风力发电 | Wind Turbines |
| ● 充电装置 | Power Charging Equipment |
| ● 智能电网 | Smart Grid |
| ● 高可靠性逆变器 | High Reliability Inverter |

| 特点 | Features |
|---------------------|------------------------------------|
| ● 铜基板 | Cu Baseplate |
| ● 增强型氧化铝衬板 | Enhanced Al_2O_3 Substrates |
| ● 高热循环能力 | High Thermal Cycling Capability |
| ● 10 μ s 短路承受能力 | 10 μ s Short Circuit Withstand |

电路结构 Circuit Configuration


 图 1. 电路结构
 Fig. 1 Circuit configuration

模块外形 Module Appearance


 图 2. 模块外形
 Fig. 2 Module appearance

模块标签说明



Module Label Code Instruction

| 数据位置 | 数据内容 |
|---------------|-------------------------------|
| Data position | Content of data |
| 1—8 | 模块批次号 Module batch number |
| 9—12 | 模块序列号 Module serial number |

最大额定值
Absolute Maximum Ratings

| 符号 Symbol | 参数名称 Parameter | 测试条件 Test Conditions | 数值 Value | 单位 Unit |
|--------------|--|--|-------------|-----------------------|
| V_{CES} | 集电极-发射极电压 Collector-emitter voltage | $V_{GE} = 0V, T_C = 25\text{ }^\circ\text{C}$ | 1700 | V |
| V_{GES} | 栅极-发射极电压 Gate-emitter voltage | $T_C = 25\text{ }^\circ\text{C}$ | ± 20 | V |
| I_C | 集电极电流 Collector-emitter current | $T_C = 100\text{ }^\circ\text{C}, T_{vjmax} = 175\text{ }^\circ\text{C}$ | 600 | A |
| $I_{C(PK)}$ | 集电极峰值电流 Peak collector current | $t_p = 1\text{ms}$ | 1200 | A |
| P_{max} | 晶体管部分最大损耗 Max. transistor power dissipation | $T_{vj} = 175\text{ }^\circ\text{C}, T_C = 25\text{ }^\circ\text{C}$ | 3.26 | kW |
| f_t | 二极管 f_t 值 Diode f_t | $V_R = 0V, t_p = 10\text{ms}, T_{vj} = 150\text{ }^\circ\text{C}$ | 41.5 | kA^2s |
| V_{isol} | 绝缘电压(模块) Isolation voltage – per module | 短接所有端子，端子与基板间施加电压 (Connected terminals to base plate), AC RMS, 1 min, 50Hz, $T_C = 25\text{ }^\circ\text{C}$ | 3400 | V |

热和机械数据
Thermal & Mechanical Data

| 参数 Symbol | 说明 Explanation | 值 Value | 单位 Unit |
|--|--------------------------------|------------|------------|
| 爬电距离 Creepage distance | 端子-散热器 Terminal to heatsink | 14.5 | mm |
| | 端子-端子 Terminal to terminal | 13.0 | mm |
| 绝缘间隙 Clearance | 端子-散热器 Terminal to heatsink | 12.5 | mm |
| | 端子-端子 Terminal to terminal | 10.0 | mm |
| 相对漏电起痕指数 CTI (Comparative Tracking Index) | | >200 | |

热和机械数据
Thermal & Mechanical Data

| 符号 Symbol | 参数名称 Parameter | 测试条件 Test Conditions | 最小值 Min. | 典型值 Typ. | 最大值 Max. | 单位 Unit |
|---------------------|--|--|-------------|-------------|-------------|------------|
| $R_{th(J-C)}$ IGBT | IGBT 结壳热阻 Thermal resistance – IGBT | | | | 46 | K / kW |
| $R_{th(J-C)}$ Diode | 二极管结壳热阻 Thermal resistance – Diode | | | | 80 | K / kW |
| $R_{th(C-H)}$ IGBT | 接触热阻(IGBT) Thermal resistance – case to heatsink (IGBT) | 安装力矩 5Nm, 导热脂 1W/m·K Mounting torque 5Nm, with mounting grease 1W/m·K | | 33 | | K / kW |
| $R_{th(C-H)}$ Diode | 接触热阻(Diode) Thermal resistance – case to heatsink (Diode) | 安装力矩 5Nm, 导热脂 1W/m·K Mounting torque 5Nm, with mounting grease 1W/m·K | | 38 | | K / kW |
| $T_{vj\ op}$ | 工作结温 Operating junction temperature | IGBT 部分 (IGBT) | -40 | | 150 | °C |
| | | 二极管部分(Diode) | -40 | | 150 | °C |
| T_{stg} | 存储温度 Storage temperature range | | -40 | | 125 | °C |
| M | 安装力矩 Screw torque | 安装紧固用 - M5 Mounting - M5 | 3 | | 6 | Nm |
| | | 电路互连用- M6 Electrical connections - M6 | 3 | | 6 | Nm |

热敏电阻数据
NTC-Thermistor Data

| 符号 Symbol | 参数名称 Parameter | 测试条件 Test Conditions | 最小值 Min. | 典型值 Typ. | 最大值 Max. | 单位 Unit |
|--------------|--|--|-------------|-------------|-------------|------------|
| R_{25} | 额定电阻值 Rated resistance | $T_C = 25\ ^\circ\text{C}$ | | 5 | | kΩ |
| $\Delta R/R$ | R_{100} 偏差 Deviation of R_{100} | $T_C = 100\ ^\circ\text{C}$, $R_{100}=493\Omega$ | -5 | | 5 | % |
| P_{25} | 耗散功率 Power dissipation | $T_C = 25\ ^\circ\text{C}$ | | | 20 | mW |
| $B_{25/50}$ | B -值 B -value | $R_2 = R_{25}\exp [B_{25/50}(1/T_2 - 1/(298.15\text{ K}))]$ | | 3375 | | K |
| $B_{25/80}$ | B -值 B -value | $R_2 = R_{25}\exp [B_{25/80}(1/T_2 - 1/(298.15\text{ K}))]$ | | 3411 | | K |
| $B_{25/100}$ | B -值 B -value | $R_2 = R_{25}\exp [B_{25/100}(1/T_2 - 1/(298.15\text{ K}))]$ | | 3433 | | K |

电特性值
Electrical Characteristics

 除非特别声明，否则 $T_C = 25\text{ }^\circ\text{C}$
 $T_C = 25\text{ }^\circ\text{C}$ unless otherwise stated

| 符号 Symbol | 参数名称 Parameter | 条件 Test Conditions | 最小值 Min. | 典型值 Typ. | 最大值 Max. | 单位 Unit |
|----------------------|---|--|-------------|-------------|-------------|---------------|
| I_{CES} | 集电极截止电流 Collector cut-off current | $V_{GE} = 0V, V_{CE} = V_{CES}$ | | | 1 | mA |
| | | $V_{GE} = 0V, V_{CE} = V_{CES}, T_{vj} = 125\text{ }^\circ\text{C}$ | | | 15 | mA |
| | | $V_{GE} = 0V, V_{CE} = V_{CES}, T_{vj} = 150\text{ }^\circ\text{C}$ | | | 30 | mA |
| I_{GES} | 栅极漏电流 Gate leakage current | $V_{GE} = \pm 20V, V_{CE} = 0V$ | | | 0.5 | μA |
| $V_{GE(TH)}$ | 栅极-发射极阈值电压 Gate threshold voltage | $I_C = 15\text{mA}, V_{GE} = V_{CE}$ | 5.60 | 6.20 | 6.80 | V |
| $V_{CE(sat)}^{(*1)}$ | 集电极-发射极饱和电压 Collector-emitter saturation voltage | $V_{GE} = 15V, I_C = 600A$ | | 1.80 | 2.20 | V |
| | | $V_{GE} = 15V, I_C = 600A, T_{vj} = 125\text{ }^\circ\text{C}$ | | 2.20 | | V |
| | | $V_{GE} = 15V, I_C = 600A, T_{vj} = 150\text{ }^\circ\text{C}$ | | 2.30 | | V |
| I_F | 二极管正向直流电流 Diode forward current | DC | | 600 | | A |
| I_{FRM} | 二极管正向重复峰值电流 Diode peak forward current | $t_p = 1\text{ms}$ | | 1200 | | A |
| $V_F^{(*1)}$ | 二极管正向电压 Diode forward voltage | $I_F = 600A, V_{GE} = 0$ | | 1.85 | 2.25 | V |
| | | $I_F = 600A, V_{GE} = 0, T_{vj} = 125\text{ }^\circ\text{C}$ | | 2.10 | | V |
| | | $I_F = 600A, V_{GE} = 0, T_{vj} = 150\text{ }^\circ\text{C}$ | | 2.10 | | V |
| I_{SC} | 短路电流 Short circuit current | $T_{vj} = 150\text{ }^\circ\text{C}, V_{CC} = 1000V,$ $V_{GE} \leq 15V, t_p \leq 10\mu\text{s},$ $V_{CE(max)} = V_{CES} - L^{(*2)} \times di/dt,$ IEC 60747-9 | | 2400 | | A |

注意: 1.(*1) 表示该参数的测试点为辅助母排端子 (*1) indicates it is measured at the auxiliary busbar terminal),

Note: 2.(*2) 表示 L 是电路杂散电感加上 L_M (*2) indicates L is the circuit stray inductance plus L_M).

电特性值
Electrical Characteristics

 除非特别声明，否则 $T_C = 25\text{ }^\circ\text{C}$
 $T_C = 25\text{ }^\circ\text{C}$ unless otherwise stated

| 符号 Symbol | 参数名称 Parameter | 条件 Test Conditions | 最小值 Min. | 典型值 Typ. | 最大值 Max. | 单位 Unit |
|---------------|--|---|-------------|-------------|-------------|------------|
| C_{ies} | 输入电容 Input capacitance | $V_{CE} = 25V, V_{GE} = 0V, f = 100kHz$ | | 96 | | nF |
| Q_g | 栅极电荷 Gate charge | $\pm 15V$ | | 6.1 | | μC |
| C_{res} | 反向传输电容 Reverse transfer capacitance | $V_{CE} = 25V, V_{GE} = 0V, f = 100kHz$ | | 0.7 | | nF |
| L_M | 模块电感 Module inductance | | | 20 | | nH |
| $R_{CC'+EE'}$ | 模块引线电阻，端子-芯片 Module lead resistance, terminal-chip | | | 1 | | m Ω |

电特性值
Electrical Characteristics

| 符号 Symbol | 参数名称 Parameter | 测试条件 Test Conditions | 最小值 Min. | 典型值 Typ. | 最大值 Max. | 单位 Unit | |
|--------------|---|--|------------------------|-------------|-------------|------------|----|
| $t_{d(off)}$ | 关断延迟时间 Turn-off delay time | $I_C = 600A,$ $V_{CE} = 900V,$ $V_{GE} = \pm 15V,$ $R_{G(OFF)} = 1\Omega,$ $L_S = 60nH,$ $dv/dt = 5000V/\mu s$ ($T_{vj} = 150^\circ C$). | $T_{vj} = 25^\circ C$ | 760 | | ns | |
| | | | $T_{vj} = 125^\circ C$ | 860 | | | |
| | | | $T_{vj} = 150^\circ C$ | 870 | | | |
| t_f | 下降时间 Fall time | | $T_{vj} = 25^\circ C$ | | 360 | | ns |
| | | | $T_{vj} = 125^\circ C$ | | 500 | | |
| | | | $T_{vj} = 150^\circ C$ | | 535 | | |
| E_{OFF} | 关断损耗 Turn-off energy loss | | $T_{vj} = 25^\circ C$ | | 135 | | mJ |
| | | | $T_{vj} = 125^\circ C$ | | 183 | | |
| | | | $T_{vj} = 150^\circ C$ | | 194 | | |
| $t_{d(on)}$ | 开通延迟时间 Turn-on delay time | $T_{vj} = 25^\circ C$ | | 285 | | ns | |
| | | $T_{vj} = 125^\circ C$ | | 295 | | | |
| | | $T_{vj} = 150^\circ C$ | | 300 | | | |
| t_r | 上升时间 Rise time | $T_{vj} = 25^\circ C$ | | 81 | | ns | |
| | | $T_{vj} = 125^\circ C$ | | 85 | | | |
| | | $T_{vj} = 150^\circ C$ | | 86 | | | |
| E_{ON} | 开通损耗 Turn-on energy loss | $T_{vj} = 25^\circ C$ | | 45 | | mJ | |
| | | $T_{vj} = 125^\circ C$ | | 61 | | | |
| | | $T_{vj} = 150^\circ C$ | | 67 | | | |
| Q_{rr} | 二极管反向恢复电荷 Diode reverse recovery charge | $T_{vj} = 25^\circ C$ | | 155 | | μC | |
| | | $T_{vj} = 125^\circ C$ | | 250 | | | |
| | | $T_{vj} = 150^\circ C$ | | 270 | | | |
| I_{rr} | 二极管反向恢复电流 Diode reverse recovery current | $I_F = 600A,$ $V_{CE} = 900V,$ $- di_F/dt = 7700A/\mu s$ ($T_{vj} = 150^\circ C$). | $T_{vj} = 25^\circ C$ | 720 | | A | |
| | | | $T_{vj} = 125^\circ C$ | 810 | | | |
| | | | $T_{vj} = 150^\circ C$ | 830 | | | |
| E_{rec} | 二极管反向恢复损耗 Diode reverse recovery energy | | $T_{vj} = 25^\circ C$ | | 123 | | mJ |
| | | | $T_{vj} = 125^\circ C$ | | 192 | | |
| | | | $T_{vj} = 150^\circ C$ | | 209 | | |

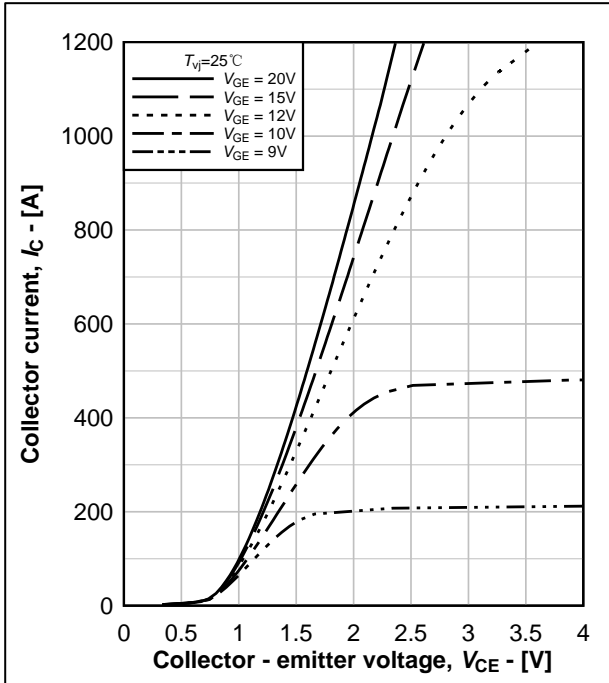


图 3. IGBT 输出特性典型曲线, $I_C = f(V_{CE})$

Fig.3 Typical IGBT output characteristics, $I_C = f(V_{CE})$

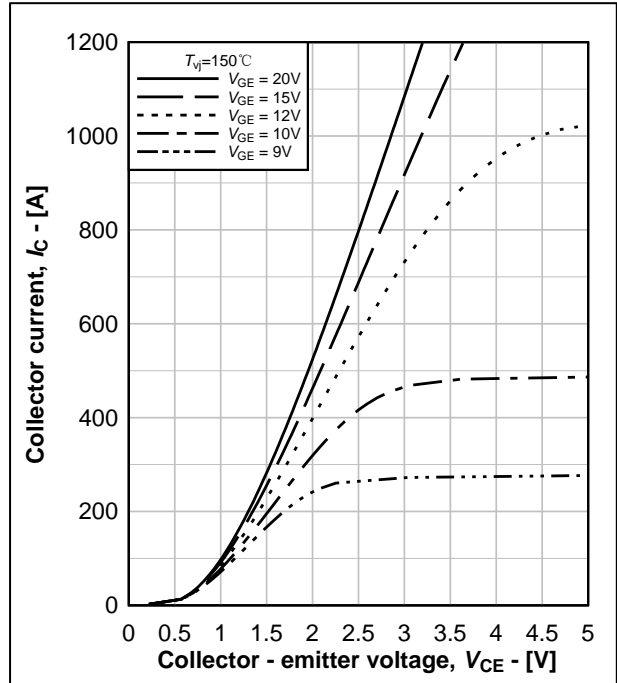


图 4. IGBT 输出特性典型曲线, $I_C = f(V_{CE})$

Fig.4 Typical IGBT output characteristics, $I_C = f(V_{CE})$

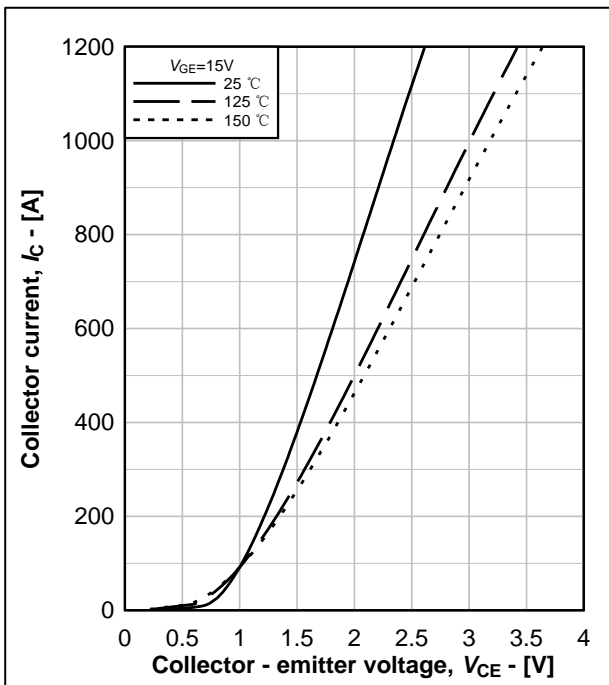


图 5. IGBT 输出特性典型曲线, $I_C = f(V_{CE})$

Fig.5 Typical IGBT output characteristics, $I_C = f(V_{CE})$

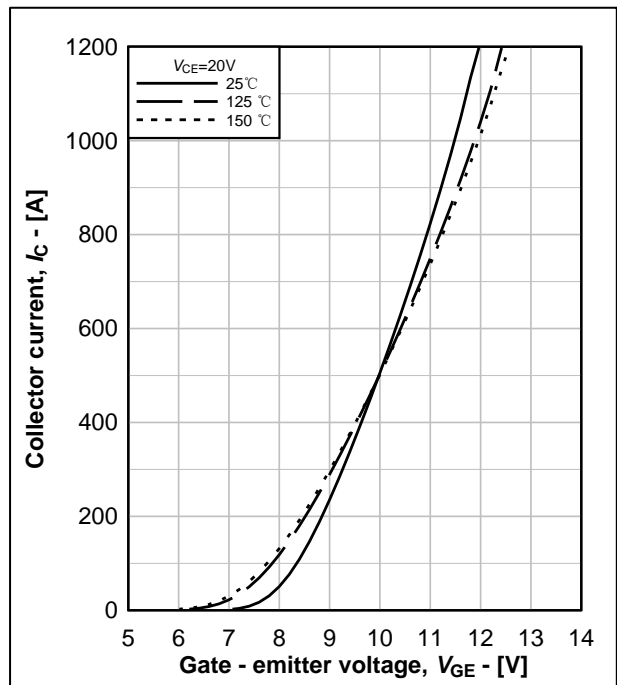


图 6. IGBT 传输特性典型曲线, $I_C = f(V_{GE})$

Fig.6 Typical IGBT transfer characteristics, $I_C = f(V_{GE})$

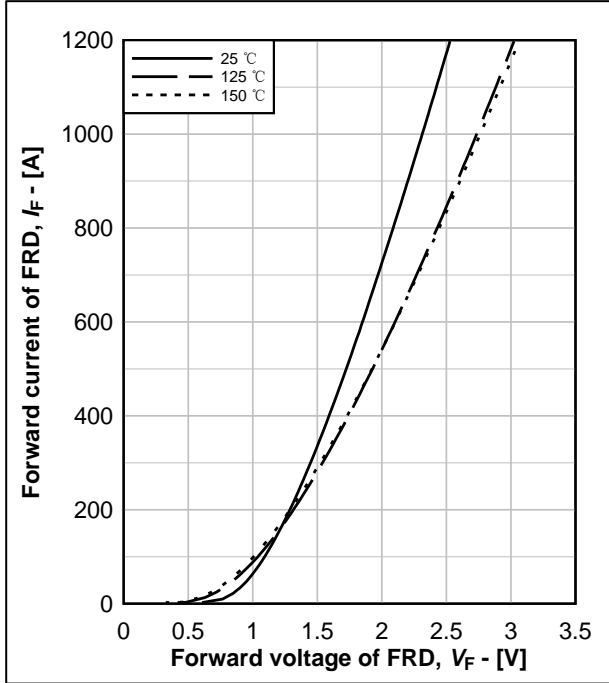


图 7. FRD 输出特性典型曲线, $I_F = f(V_F)$

Fig.7 Typical FRD output characteristics, $I_F = f(V_F)$

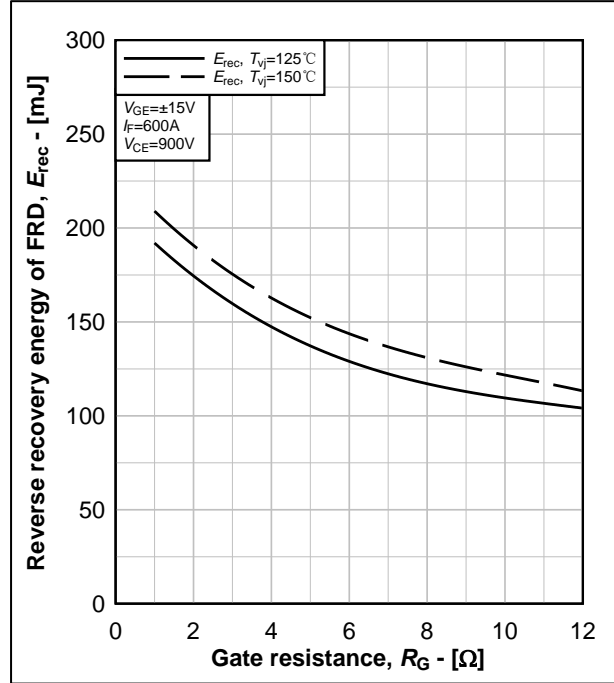


图 8. FRD 反向恢复能耗典型曲线, $E_{rec} = f(R_G)$

Fig.8 Typical FRD E_{rec} $E_{rec} = f(R_G)$

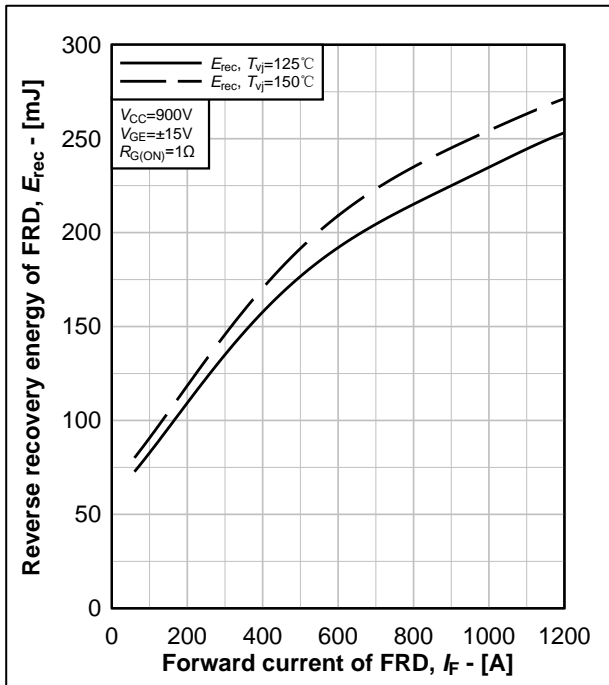


图 9. FRD 反向恢复能耗典型曲线, $E_{rec} = f(I_F)$

Fig.9 Typical FRD E_{rec} $E_{rec} = f(I_F)$

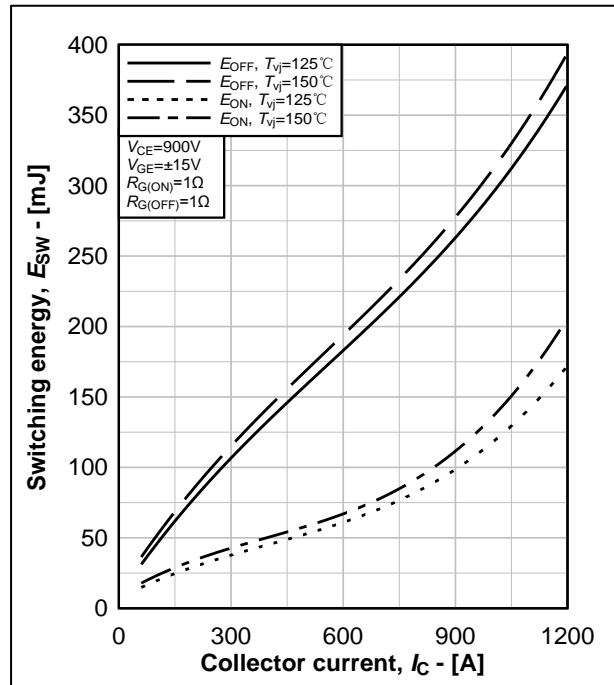


图 10. IGBT 开关能耗典型曲线, $E_{ON} = f(I_C)$, $E_{OFF} = f(I_C)$

Fig.10 Typical IGBT switching energy, $E_{ON} = f(I_C)$, $E_{OFF} = f(I_C)$

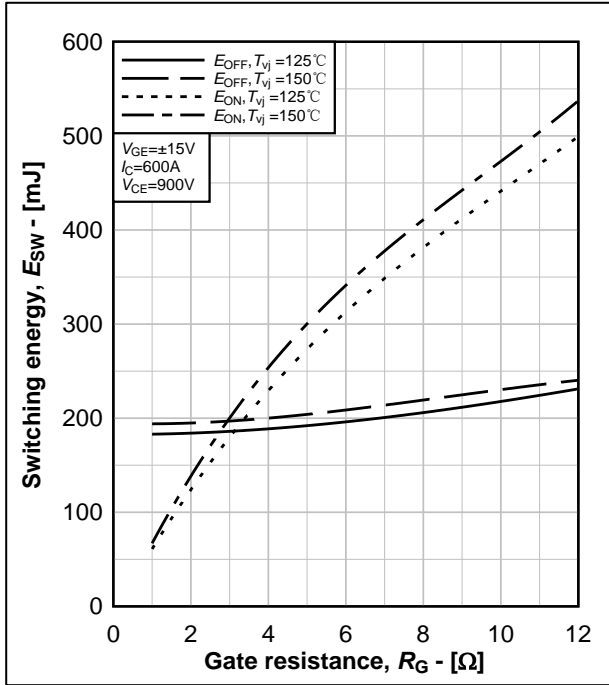

 图 11. IGBT 开关能耗典型曲线, $E_{ON} = f(R_G)$, $E_{OFF} = f(R_G)$

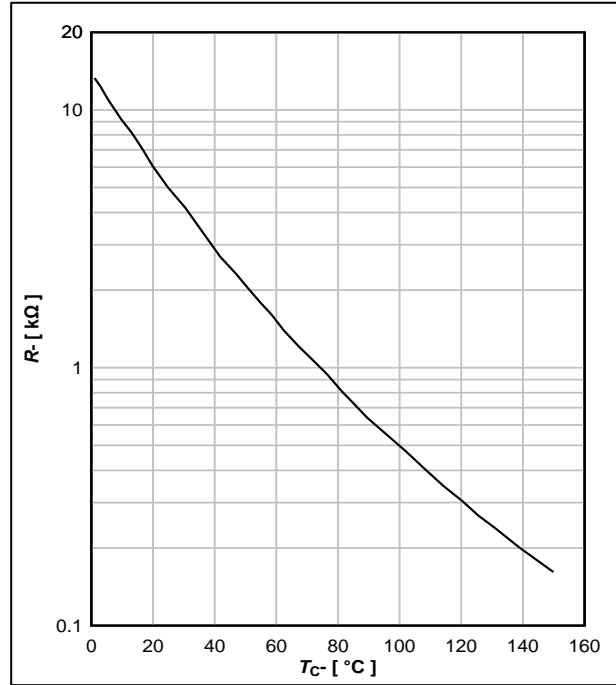
 Fig.11 Typical IGBT switching energy, $E_{ON} = f(R_G)$, $E_{OFF} = f(R_G)$

 图 12. 热敏电阻典型特性曲线, $R = f(T_C)$

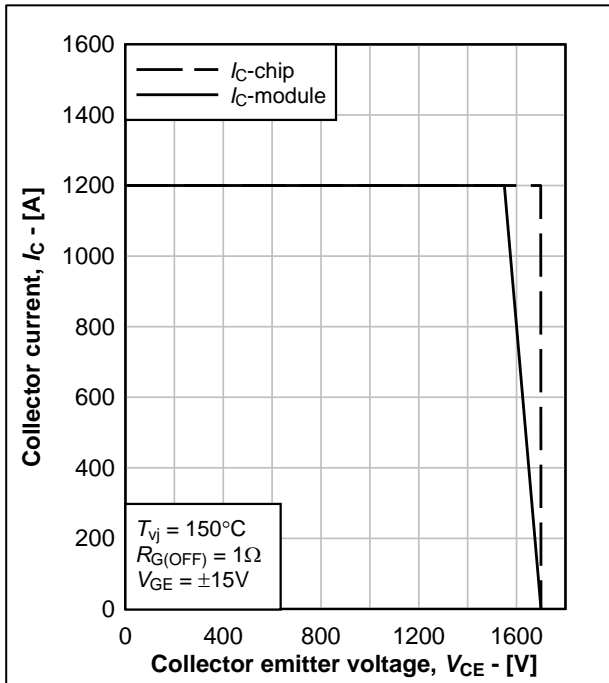
 Fig.12 Typical NTC thermistor characteristic, $R = f(T_C)$

 图 13. IGBT 反偏安全工作区, $I_C = f(V_{CE})$

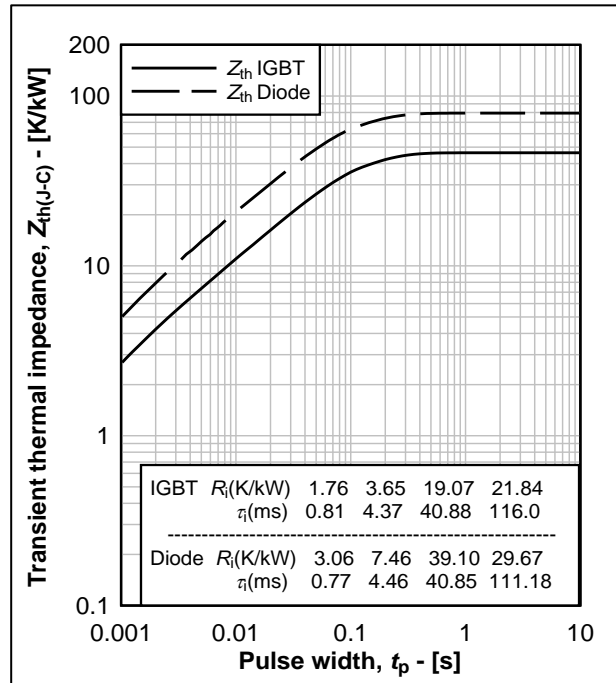
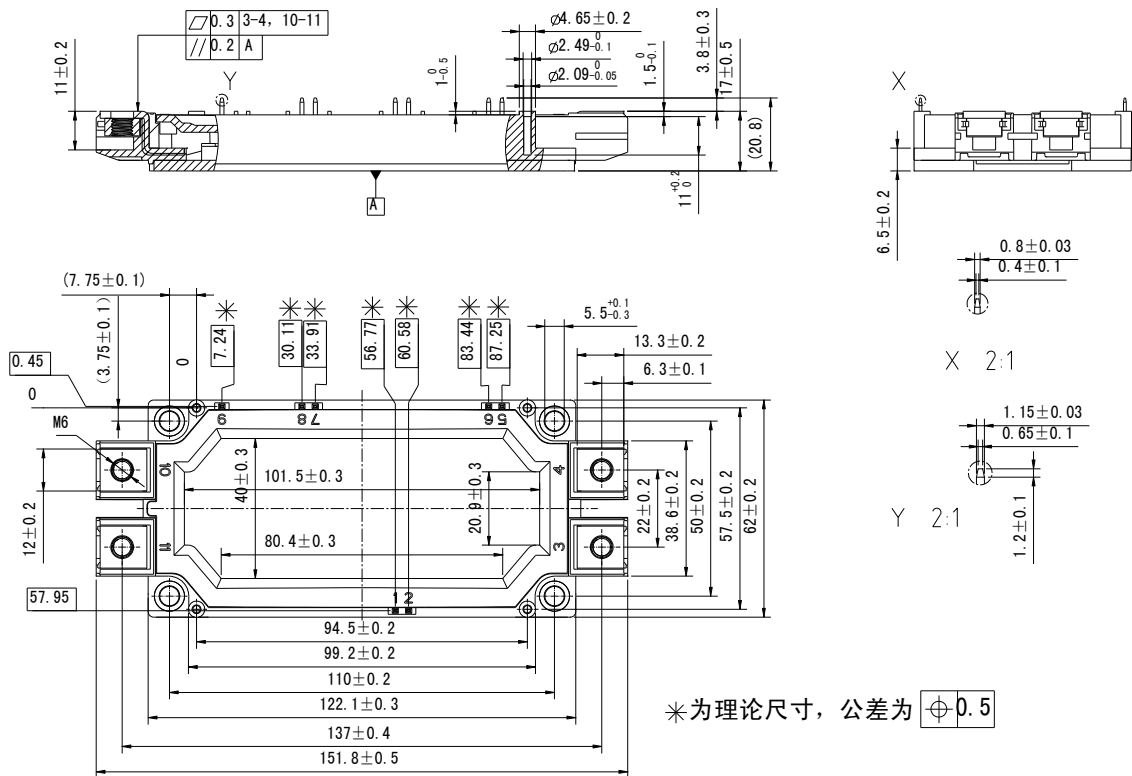
 Fig.13 Reverse bias safe operating area of IGBT, $I_C = f(V_{CE})$

 图 14. 瞬态热阻抗曲线, $Z_{th(J-C)} = f(t_p)$

 Fig.14 Transient thermal impedance, $Z_{th(J-C)} = f(t_p)$



重量 Weight: 345g 模块外观类型 Module outline code: M1

图 15. 模块外观尺寸

Fig. 15 Module outlines

株洲中车时代半导体有限公司
ZHUZHOU CRRC TIMES SEMICONDUCTOR CO., LTD

| | | | |
|------|-----------|---|---|
| 地 址 | Address | 湖南省株洲市石峰区田心工业园 | Tianxin Industrial Park, Shifeng District, ZhuZhou City, Hunan Province, China |
| 邮 编 | Zipcode | 412001 | |
| 电 话 | Telephone | +86 (0)731-28498268, 28498238, 28493472 | |
| 传 真 | Fax | +86 (0)731-28498851, 28498494 | |
| 电子邮箱 | Email | sbu@crcczic.cc | |
| 网 址 | Web Site | http://www.sbu.crcczic.cc | |

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